

## Soldered SAM data sheet SAM- $\lambda$ -A- $\tau$ -4.0-25.0s-c or 4.0-25.0s-e

GaAs chip area                      standard:        4.0 mm x 4.0 mm  
   optional:        other dimensions on request

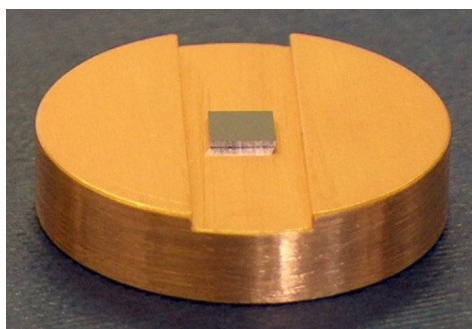
Chip thickness                      standard:        450  $\mu$ m

Front side protection              the SAM is protected with a dielectric front layer.

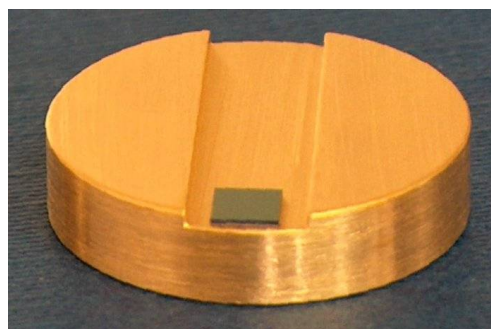
The SAM chip is soldered on a gold plated Cu-cylinder with 25.0 mm  $\varnothing$  using a Sn/Bi solder. The solder ensures alow thermal resistance between the SAM and the heat sink

- The **standard** position of the SAM is at the center of the mount  $\rightarrow$  x = 4.0-25.0s-c.
- **Optional** the SAM can be mounted at the edge of the mount without extra charges  
 $\rightarrow$  x = 4.0-25.0s-e.

Center mounted SAM



Edge mounted SAM



### Mount

Cu-cylinder,  $\varnothing = 25.0$  mm  
l = 6.0 mm

